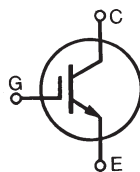


1200V XPT™ IGBT GenX3™

IXYR100N120C3

(Electrically Isolated Tab)

High-Speed IGBT
for 20-50 kHz Switching



$$V_{CES} = 1200V$$

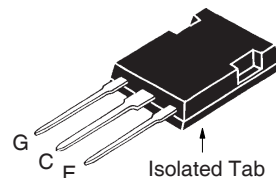
$$I_{C110} = 56A$$

$$V_{CE(sat)} \leq 3.50V$$

$$t_{fi(typ)} = 110ns$$

| Symbol | Test Conditions | Maximum Ratings | |
|-------------------------------|---|---|------------|
| V_{CES} | $T_J = 25^\circ C$ to $175^\circ C$ | 1200 | V |
| V_{CGR} | $T_J = 25^\circ C$ to $175^\circ C$, $R_{GE} = 1M\Omega$ | 1200 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ C$ (Chip Capability) | 110 | A |
| I_{C110} | $T_C = 110^\circ C$ | 56 | A |
| I_{CM} | $T_C = 25^\circ C$, 1ms | 450 | A |
| I_A | $T_C = 25^\circ C$ | 50 | A |
| E_{AS} | $T_C = 25^\circ C$ | 1.2 | J |
| SSOA (RBSOA) | $V_{GE} = 15V$, $T_{VJ} = 150^\circ C$, $R_G = 1\Omega$ Clamped Inductive Load | $I_{CM} = 200$ @ $V_{CE} \leq V_{CES}$ | A |
| P_C | $T_C = 25^\circ C$ | 484 | W |
| T_J | | -55 ... +175 | $^\circ C$ |
| T_{JM} | | 175 | $^\circ C$ |
| T_{stg} | | -55 ... +175 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ C$ |
| T_{SOLD} | 1.6 mm (0.062in.) from Case for 10s | 260 | $^\circ C$ |
| V_{ISOL} | 50/60 Hz, 1 Minute | 2500 | V~ |
| F_C | Mounting Force | 20..120/4.5..27 | N/lb. |
| Weight | | 5 | g |

ISOPLUS247™



G = Gate C = Collector
E = Emitter

Features

- Optimized for Low Switching Losses
- Square RBSOA
- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V~ Electrical Isolation
- Positive Thermal Coefficient of $V_{ce(sat)}$
- Avalanche Rated
- High Current Handling Capability

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- High Frequency Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

| Symbol | Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified) | Characteristic Values | | |
|---------------|---|-----------------------|------|-----------------------|
| | | Min. | Typ. | Max. |
| BV_{CES} | $I_C = 250\mu A$, $V_{GE} = 0V$ | 1200 | | V |
| $V_{GE(th)}$ | $I_C = 250\mu A$, $V_{CE} = V_{GE}$ | 3.0 | | 5.0 V |
| I_{CES} | $V_{CE} = V_{CES}$, $V_{GE} = 0V$ $T_J = 150^\circ C$ | | | 10 μA 1.25 mA |
| I_{GES} | $V_{CE} = 0V$, $V_{GE} = \pm 20V$ | | | ± 100 nA |
| $V_{CE(sat)}$ | $I_C = 100A$, $V_{GE} = 15V$, Note 1 $T_J = 150^\circ C$ | 2.96 3.78 | | 3.50 V V |

| Symbol Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified) | | Characteristic Values | | |
|--|--|---|-------|---------------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $I_C = 60\text{A}, V_{CE} = 10\text{V}, \text{Note 1}$ | 30 | 50 | S |
| C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | | 4950 | pF |
| C_{oes} | | | 356 | pF |
| C_{res} | | | 120 | pF |
| $Q_{g(on)}$ | $I_C = I_{C110}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$ | | 260 | nC |
| Q_{ge} | | | 47 | nC |
| Q_{gc} | | | 102 | nC |
| $t_{d(on)}$ | Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C110}, V_{GE} = 15\text{V}$ $V_{CE} = 0.5 \cdot V_{CES}, R_G = 1\Omega$ Note 2 | | 27 | ns |
| t_{ri} | | | 110 | ns |
| E_{on} | | | 12.00 | mJ |
| $t_{d(off)}$ | | | 120 | ns |
| t_{fi} | | | 110 | ns |
| E_{off} | | | 4.90 | mJ |
| $t_{d(on)}$ | | Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C110}, V_{GE} = 15\text{V}$ $V_{CE} = 0.5 \cdot V_{CES}, R_G = 1\Omega$ Note 2 | | 27 |
| t_{ri} | | | 116 | ns |
| E_{on} | | | 15.00 | mJ |
| $t_{d(off)}$ | | | 146 | ns |
| t_{fi} | | | 125 | ns |
| E_{off} | | | 6.15 | mJ |
| R_{thJC} | | | | 0.31 |
| R_{thCS} | | 0.15 | | $^\circ\text{C}/\text{W}$ |

Notes:

1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.
2. Switching times & energy losses may increase for higher V_{CE} (clamp), T_J or R_G .

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

| | | | | | | | | | | |
|---|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| IXYS MOSFETs and IGBTs are covered | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| by one or more of the following U.S. patents: | 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

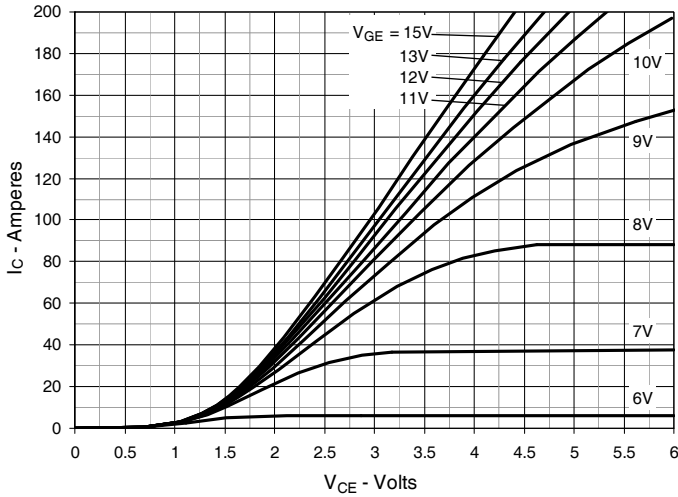
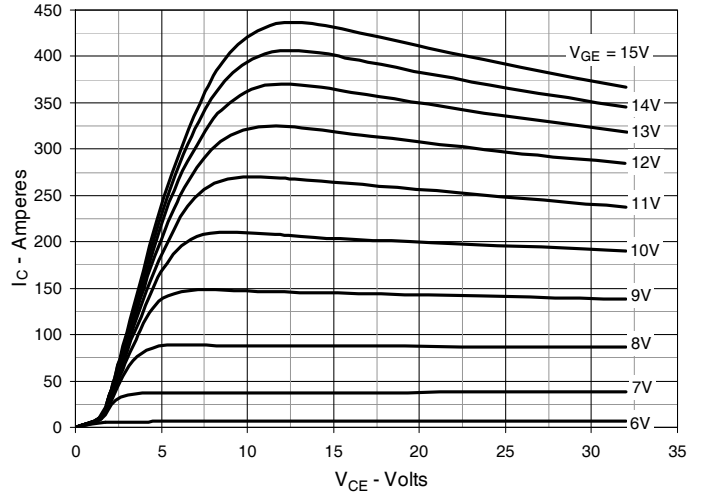
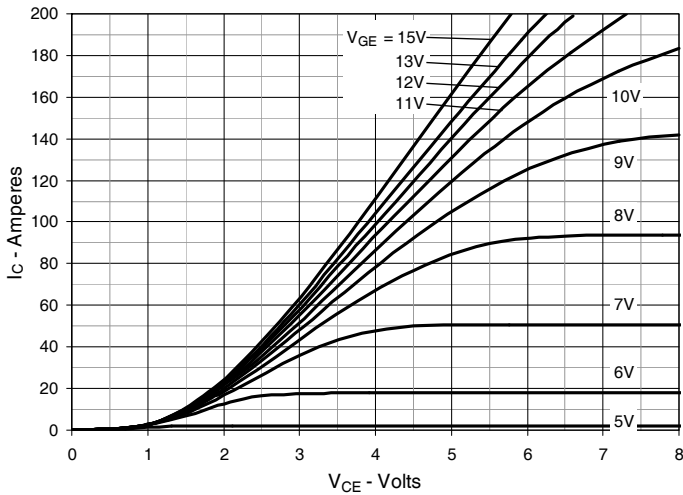
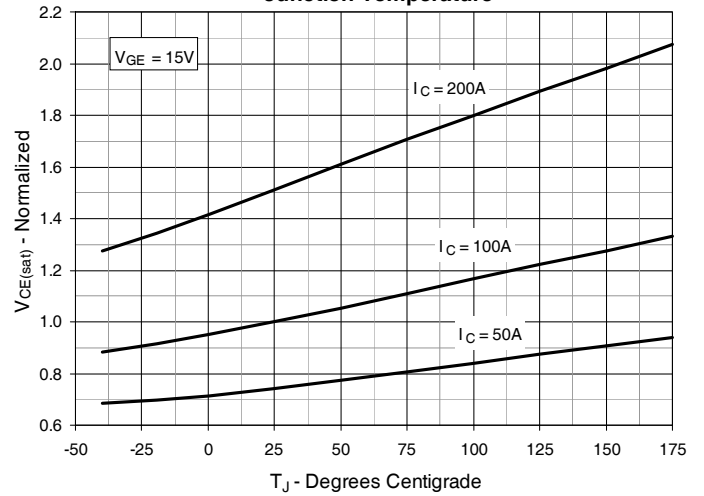
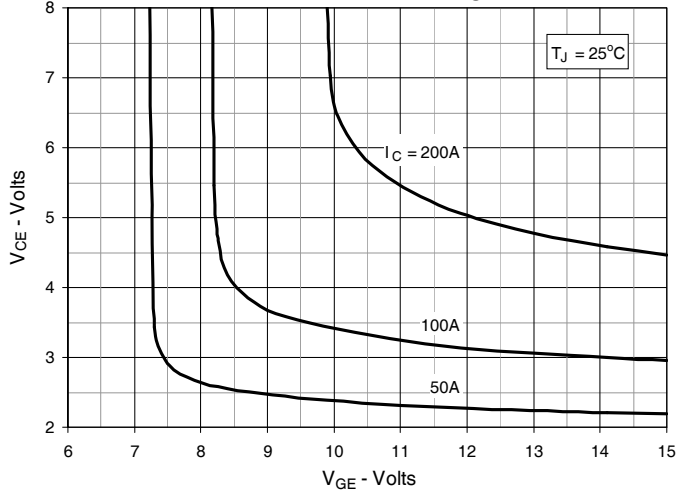
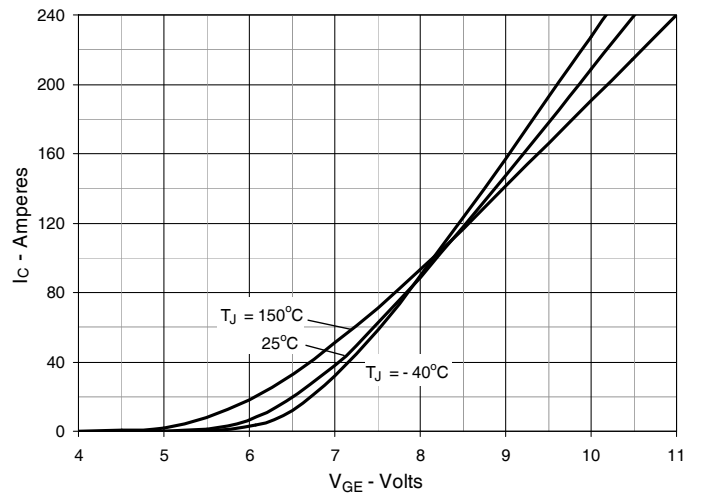
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

Fig. 6. Input Admittance


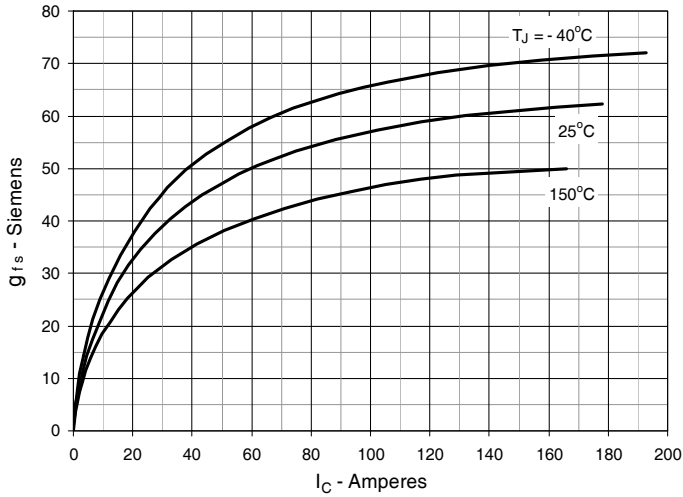
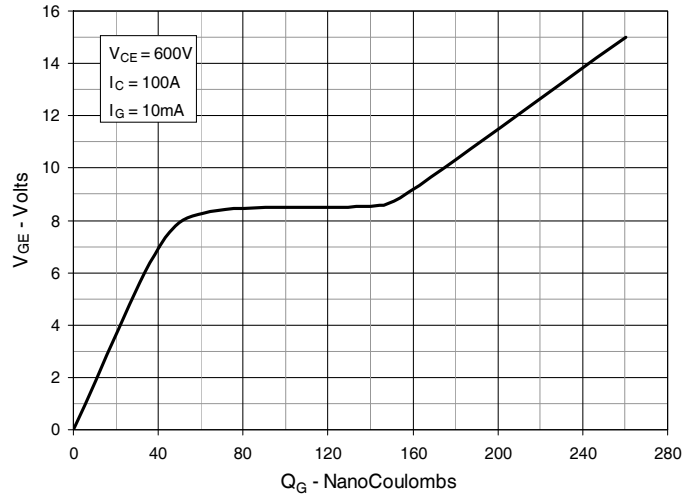
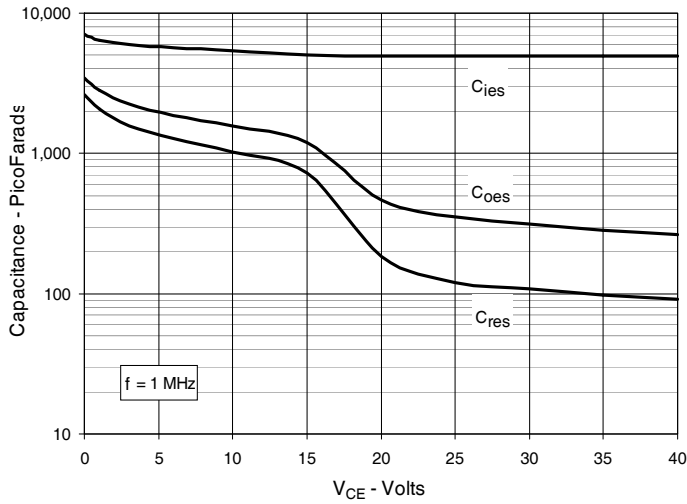
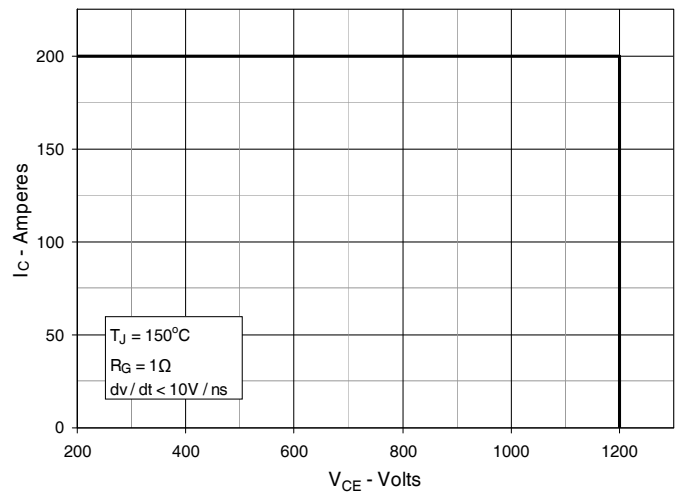
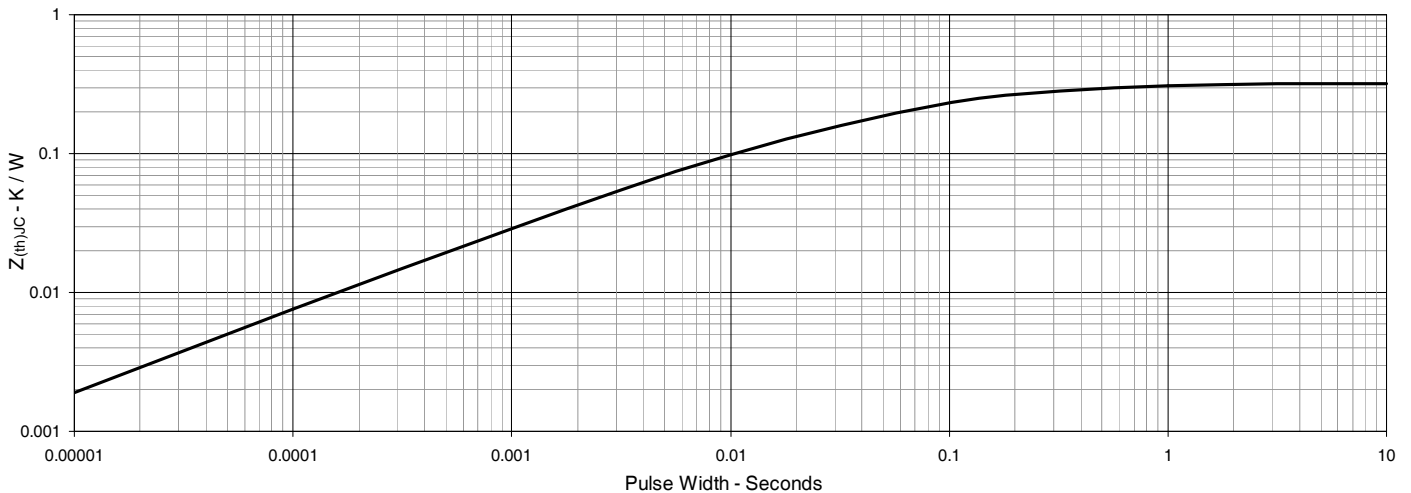
Fig. 7. Transconductance

Fig. 8. Gate Charge

Fig. 9. Capacitance

Fig. 10. Reverse-Bias Safe Operating Area

Fig. 11. Maximum Transient Thermal Impedance


Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

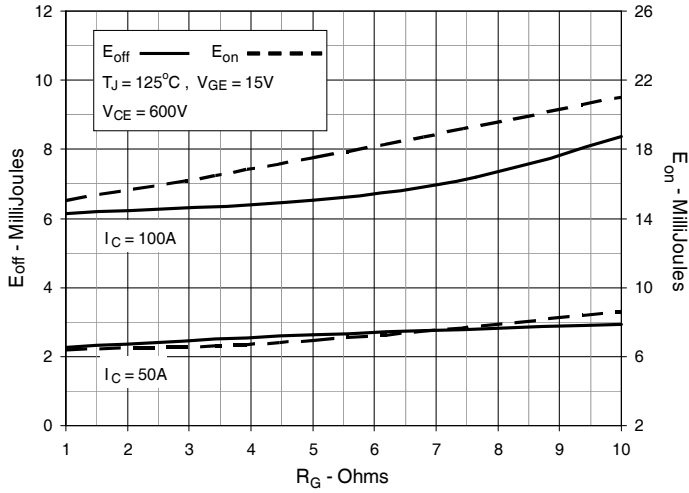


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

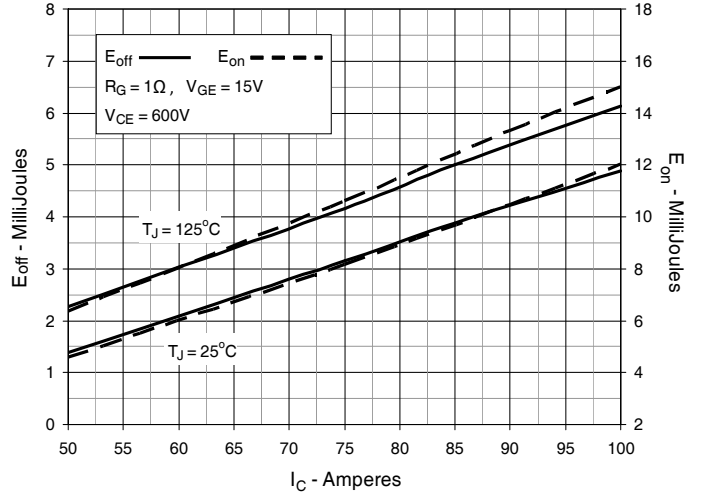


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

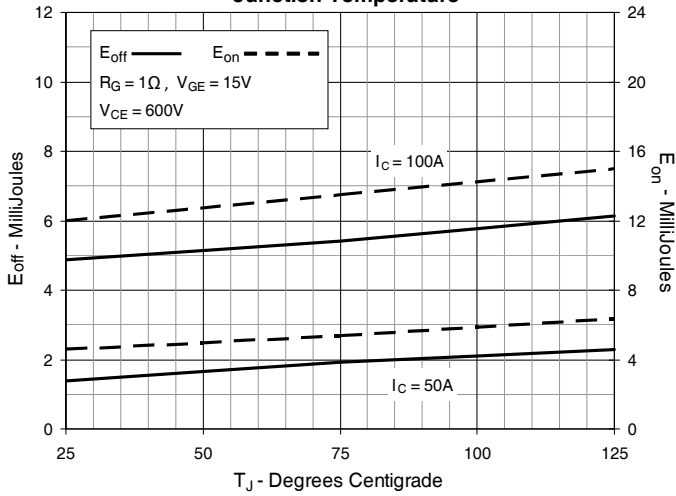


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

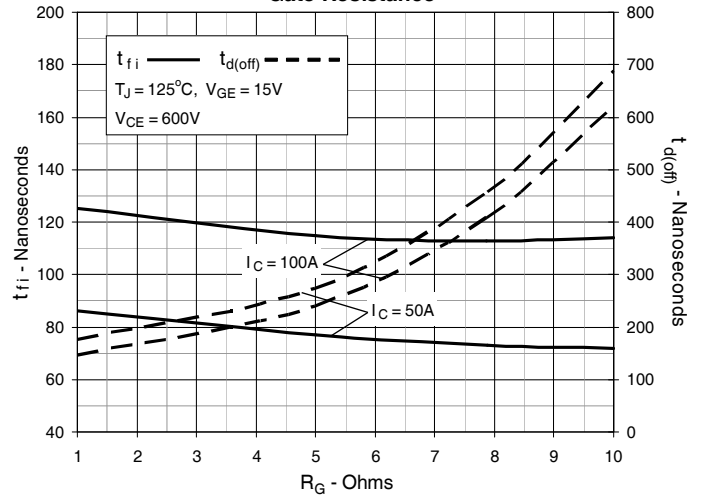


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

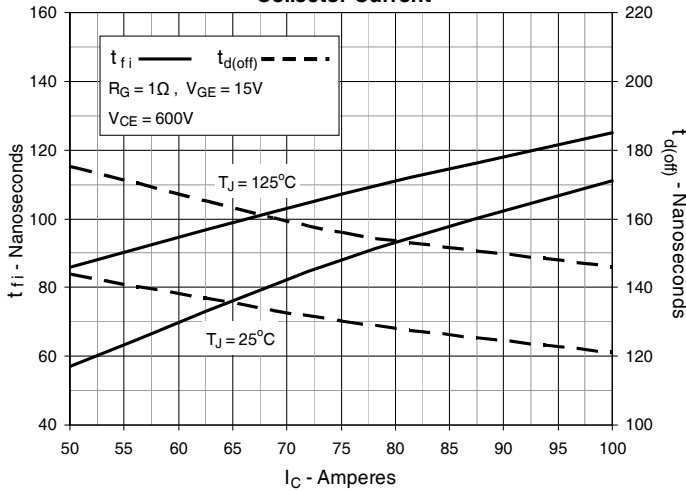


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

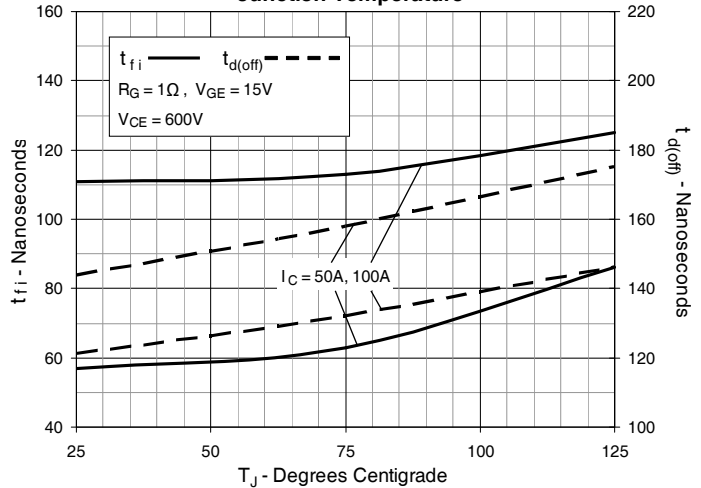


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

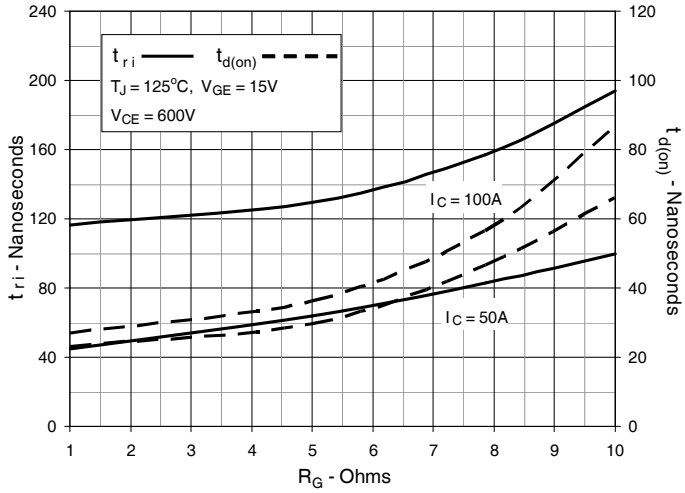


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

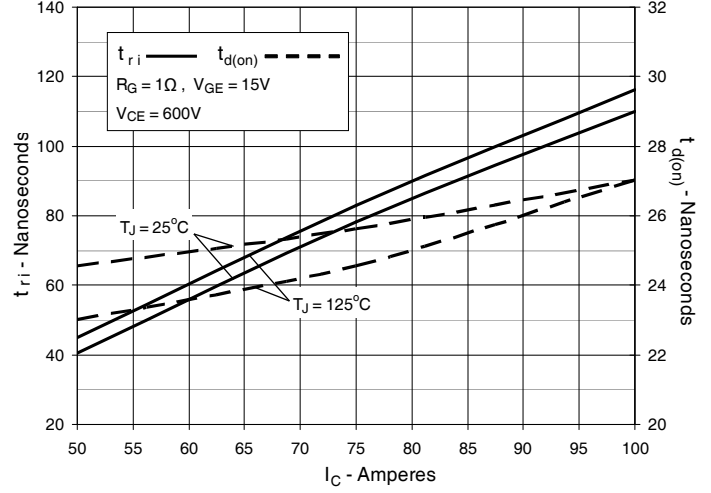
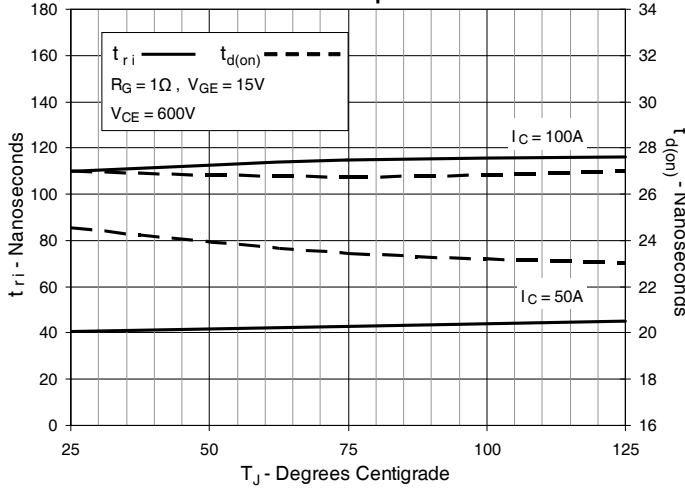
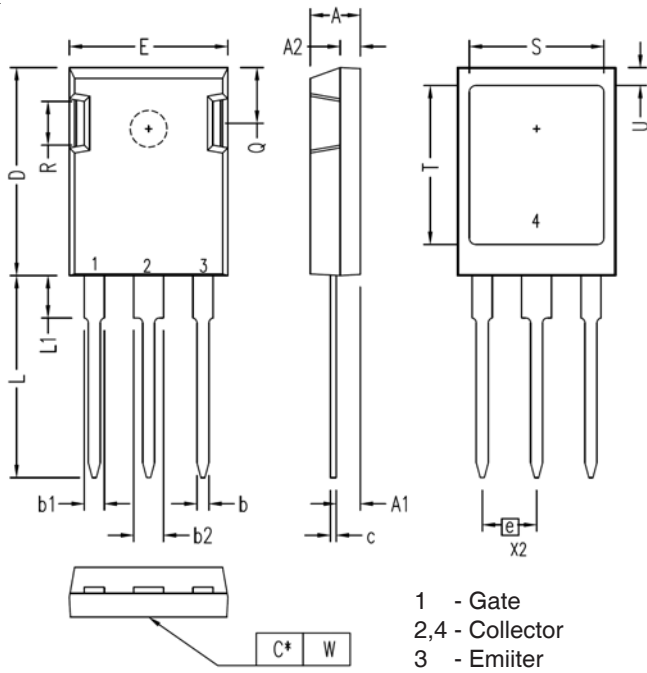


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



ISOPLUS247 (IXYR) Outline


| SYM | INCHES | | MILLIMETERS | |
|-----|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .090 | .100 | 2.29 | 2.54 |
| A2 | .075 | .085 | 1.91 | 2.16 |
| b | .045 | .055 | 1.14 | 1.40 |
| b1 | .075 | .085 | 1.91 | 2.15 |
| b2 | .115 | .126 | 2.92 | 3.20 |
| C | .024 | .033 | 0.61 | 0.83 |
| D | .819 | .840 | 20.80 | 21.34 |
| E | .620 | .635 | 15.75 | 16.13 |
| e | .215 BSC | | 5.45 BSC | |
| L | .780 | .811 | 19.81 | 20.60 |
| L1 | .150 | .172 | 3.81 | 4.38 |
| Q | .220 | .244 | 5.59 | 6.20 |
| R | .170 | .191 | 4.32 | 4.85 |
| S | .520 | .540 | 13.21 | 13.72 |
| T | .620 | .640 | 15.75 | 16.26 |
| U | .065 | .080 | 1.65 | 2.03 |
| W | 0 | .004 | 0 | 0.10 |

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.
 C* - Convex bow of substrate is typ<0.04mm over plastic surface level of device bottom side.
 LEAD FINISH - External leads are Pb free solder dip.